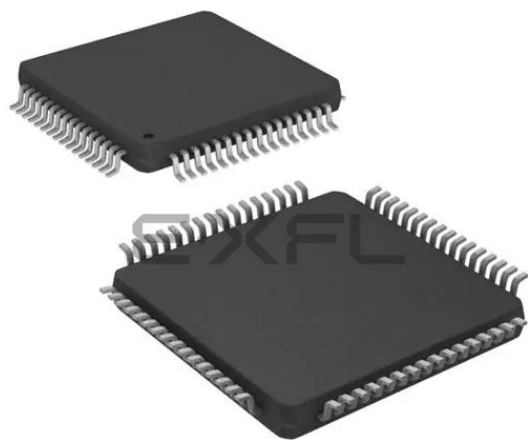




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Details

Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	50
Program Memory Size	192KB (96K x 16)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atxmega192c3-an

33.2.5 I/O Pin Characteristics

The I/O pins comply with the JEDEC LVTTTL and LVCMOS specification and the high- and low-level input and output voltage limits reflect or exceed this specification.

Table 33-36. I/O Pin Characteristics

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
$I_{OH}^{(1)}/I_{OL}^{(2)}$	I/O pin source/sink current			-15		15	mA
V_{IH}	High level input voltage	$V_{CC} = 2.4 - 3.6V$		$0.7 \cdot V_{CC}$		$V_{CC} + 0.5$	V
		$V_{CC} = 1.6 - 2.4V$		$0.8 \cdot V_{CC}$		$V_{CC} + 0.5$	
V_{IL}	Low level input voltage	$V_{CC} = 2.4 - 3.6V$		-0.5		$0.3 \cdot V_{CC}$	
		$V_{CC} = 1.6 - 2.4V$		-0.5		$0.2 \cdot V_{CC}$	
V_{OH}	High level output voltage	$V_{CC} = 3.3V$	$I_{OH} = -4mA$	2.6	2.9		
		$V_{CC} = 3.0V$	$I_{OH} = -3mA$	2.1	2.6		
		$V_{CC} = 1.8V$	$I_{OH} = -1mA$	1.4	1.6		
V_{OL}	Low level output voltage	$V_{CC} = 3.3V$	$I_{OL} = 8mA$		0.4	0.76	
		$V_{CC} = 3.0V$	$I_{OL} = 5mA$		0.3	0.64	
		$V_{CC} = 1.8V$	$I_{OL} = 3mA$		0.2	0.46	
I_{IN}	Input leakage current I/O pin	$T = 25^{\circ}C$			<0.01	1.0	μA
R_P	Pull/Bus keeper resistor				25		$k\Omega$

- Notes:
1. The sum of all I_{OH} for PORTA and PORTB must not exceed 100mA.
The sum of all I_{OH} for PORTC, PORTD, and PORTE must for each port not exceed 200mA.
The sum of all I_{OH} for pins PF[0-5] on PORTF must not exceed 200mA.
The sum of all I_{OL} for pins PF[6-7] on PORTF, PORTR, and PDI must not exceed 100mA.
 2. The sum of all I_{OL} for PORTA and PORTB must not exceed 100mA.
The sum of all I_{OL} for PORTC, PORTD, and PORTE must for each port not exceed 200mA.
The sum of all I_{OL} for pins PF[0-5] on PORTF must not exceed 200mA.
The sum of all I_{OL} for pins PF[6-7] on PORTF, PORTR, and PDI must not exceed 100mA.

33.2.14 SPI Characteristics

Figure 33-12. SPI Timing Requirements in Master Mode

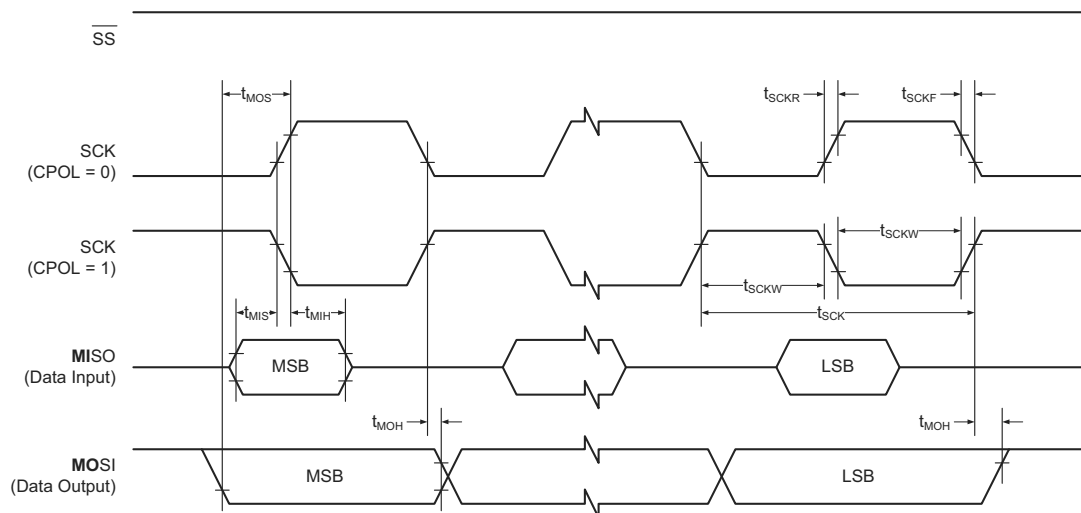
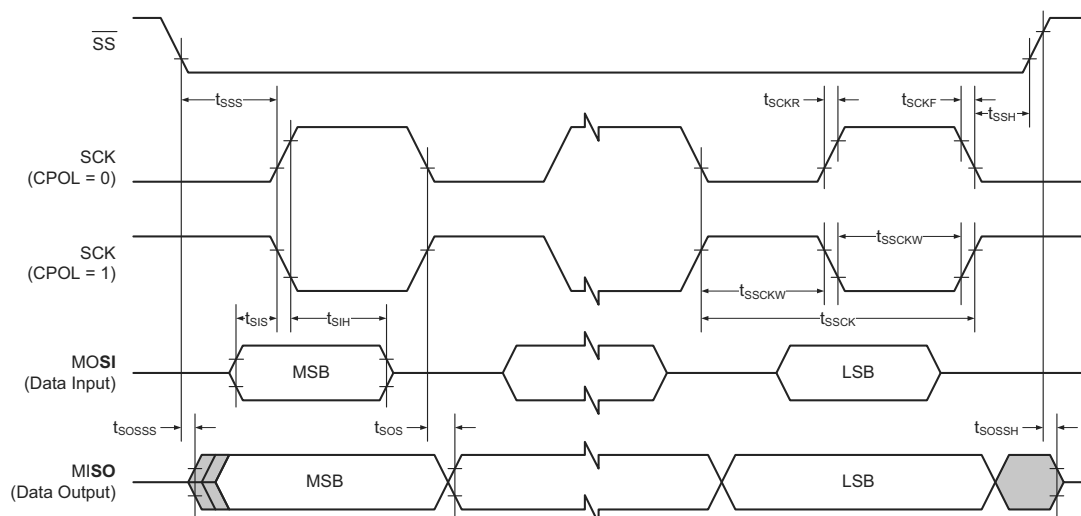


Figure 33-13. SPI Timing Requirements in Slave Mode



33.3.11 Power-on Reset Characteristics

Table 33-74. Power-on Reset Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$V_{POT-}^{(1)}$	POR threshold voltage falling V_{CC}	V_{CC} falls faster than 1V/ms	0.4	1.0		V
		V_{CC} falls at 1V/ms or slower	0.8	1.3		
V_{POT+}	POR threshold voltage rising V_{CC}			1.3	1.59	

Note: 1. V_{POT-} values are only valid when BOD is disabled. When BOD is enabled $V_{POT-} = V_{POT+}$.

33.3.12 Flash and EEPROM Memory Characteristics

Table 33-75. Endurance and Data Retention

Symbol	Parameter	Condition		Min.	Typ.	Max.	Units
	Flash	Write/Erase cycles	25°C	10K			Cycle
			85°C	10K			
			105°C	2K			
		Data retention	25°C	100			Year
			85°C	25			
			105°C	10			
	EEPROM	Write/Erase cycles	25°C	100K			Cycle
			85°C	100K			
			105°C	30K			
		Data retention	25°C	100			Year
			85°C	25			
			105°C	10			

Table 33-76. Programming Time

Symbol	Parameter	Condition		Min.	Typ. ⁽¹⁾	Max.	Units
	Chip erase ⁽²⁾	128KB Flash, EEPROM			75		ms
	Application erase	Section erase			6		
	Flash	Page erase			4		
		Page write			4		
		Atomic page erase and write			8		
	EEPROM	Page erase			4		
		Page write			4		
		Atomic page erase and write			8		

Notes: 1. Programming is timed from the 2MHz internal oscillator.
2. EEPROM is not erased if the EESAVE fuse is programmed.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
C_{XTAL1}	Parasitic capacitance XTAL1 pin			5.9		pF
C_{XTAL2}	Parasitic capacitance XTAL2 pin			8.3		
C_{LOAD}	Parasitic capacitance load			3.5		

Note: 1. Numbers for negative impedance are not tested in production but guaranteed from design and characterization.

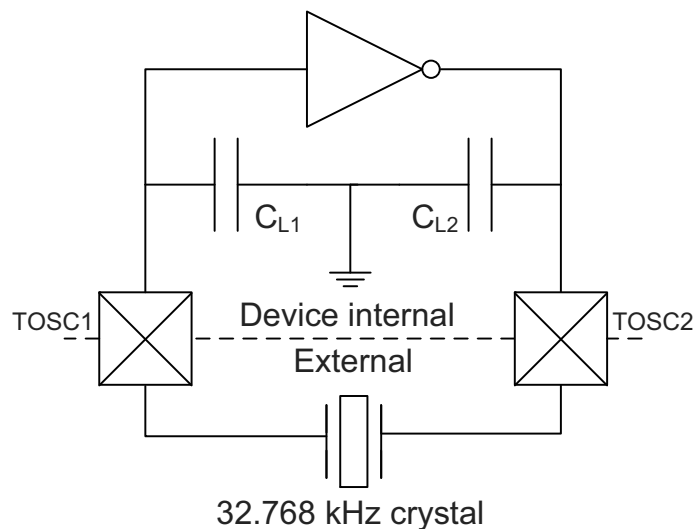
33.4.13.8 External 32.768kHz Crystal Oscillator and TOSC Characteristics

Table 33-114. External 32.768kHz Crystal Oscillator and TOSC Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ESR/R1	Recommended crystal equivalent series resistance (ESR)	Crystal load capacitance 6.5pF			60	kΩ
		Crystal load capacitance 9.0pF			35	
		Crystal load capacitance 12pF			28	
C_{TOSC1}	Parasitic capacitance TOSC1 pin			3.5		pF
C_{TOSC2}	Parasitic capacitance TOSC2 pin			3.5		
	Recommended safety factor	Capacitance load matched to crystal specification	3			

Note: See Figure 33-25 for definition.

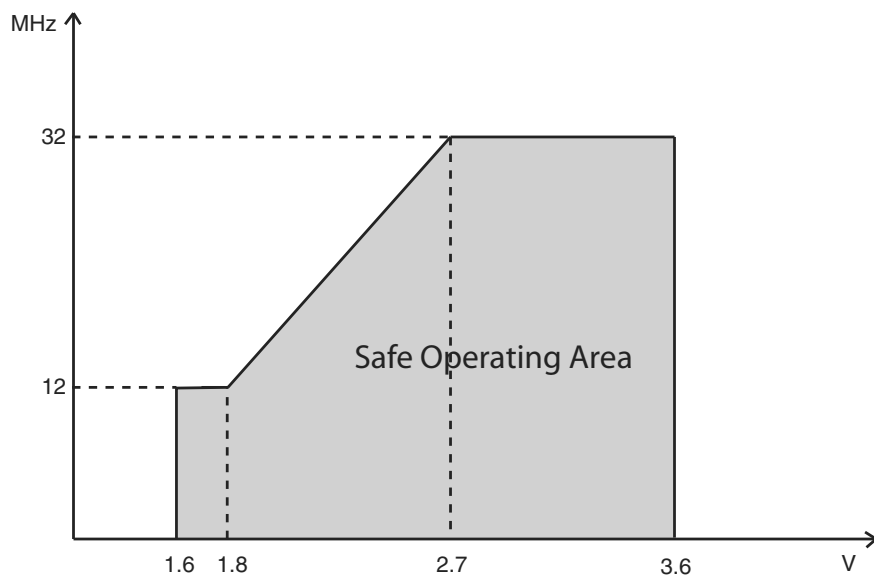
Figure 33-25. TOSC Input Capacitance



The parasitic capacitance between the TOSC pins is $C_{L1} + C_{L2}$ in series as seen from the crystal when oscillating without external capacitors.

The maximum CPU clock frequency depends on V_{CC} . As shown in Figure 33-29 the Frequency vs. V_{CC} curve is linear between $1.8V < V_{CC} < 2.7V$.

Figure 33-29. Maximum Frequency vs. V_{CC}



33.5.13.5 Internal Phase Locked Loop (PLL) Characteristics

Table 33-139. Internal PLL Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
f_{IN}	Input frequency	Output frequency must be within f_{OUT}	0.4		64	MHz
f_{OUT}	Output frequency ⁽¹⁾	$V_{CC} = 1.6 - 1.8V$	20		48	
		$V_{CC} = 2.7 - 3.6V$	20		128	
	Start-up time			25		μs
	Re-lock time			25		

Note: 1. The maximum output frequency vs. supply voltage is linear between 1.8V and 2.7V, and can never be higher than four times the maximum CPU frequency.

33.5.13.6 External Clock Characteristics

Figure 33-31. External Clock Drive Waveform

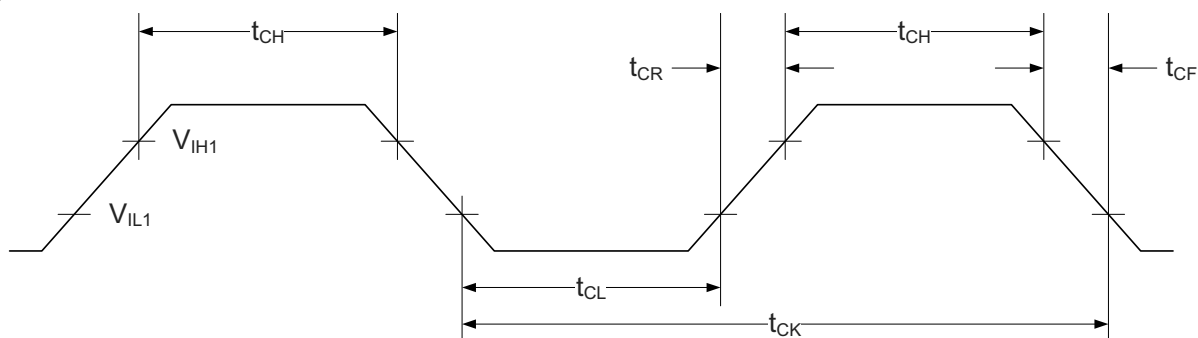


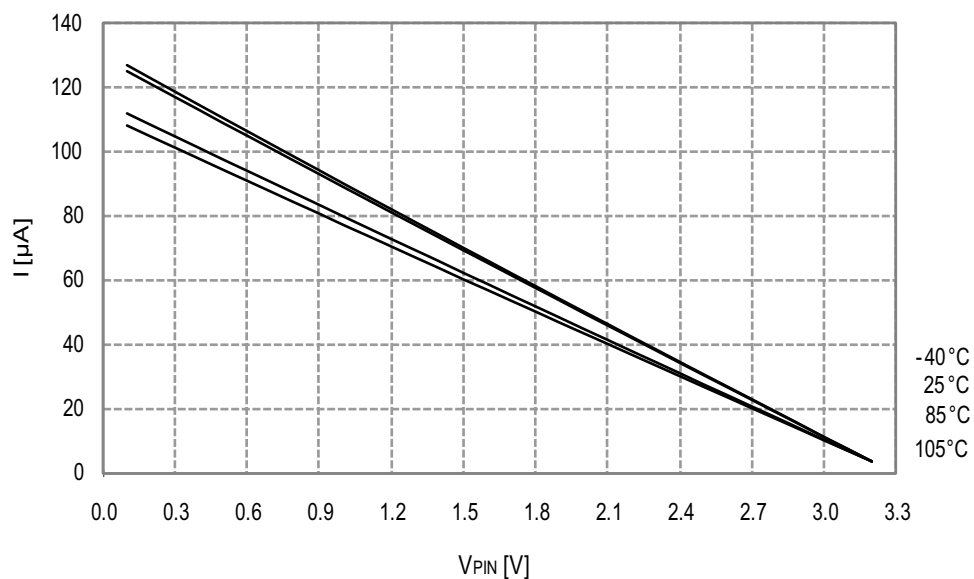
Table 33-140. External Clock used as System Clock without Prescaling

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$1/t_{CK}$	Clock Frequency ⁽¹⁾	$V_{CC} = 1.6 - 1.8V$	0		12	MHz
		$V_{CC} = 2.7 - 3.6V$	0		32	
t_{CK}	Clock Period	$V_{CC} = 1.6 - 1.8V$	83.3			ns
		$V_{CC} = 2.7 - 3.6V$	31.5			
t_{CH}	Clock High Time	$V_{CC} = 1.6 - 1.8V$	30.0			
		$V_{CC} = 2.7 - 3.6V$	12.5			
t_{CL}	Clock Low Time	$V_{CC} = 1.6 - 1.8V$	30.0			
		$V_{CC} = 2.7 - 3.6V$	12.5			
t_{CR}	Rise Time (for maximum frequency)	$V_{CC} = 1.6 - 1.8V$			10	
		$V_{CC} = 2.7 - 3.6V$			3	
t_{CF}	Fall Time (for maximum frequency)	$V_{CC} = 1.6 - 1.8V$			10	
		$V_{CC} = 2.7 - 3.6V$			3	
Δt_{CK}	Change in period from one clock cycle to the next				10	%

Note: 1. The maximum frequency vs. supply voltage is linear between 1.6V and 2.7V, and the same applies for all other parameters with supply voltage conditions.

Figure 34-21. I/O Pin Pull-up Resistor Current vs. Input Voltage

$V_{CC} = 3.3V$



34.1.2.2 Output Voltage vs. Sink/Source Current

Figure 34-22. I/O Pin Output Voltage vs. Source Current

$V_{CC} = 1.8V$

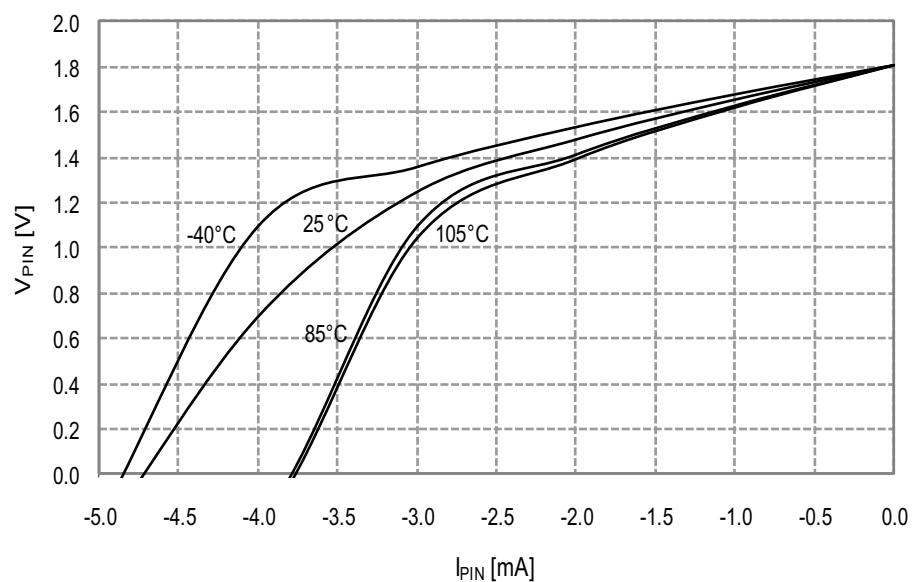
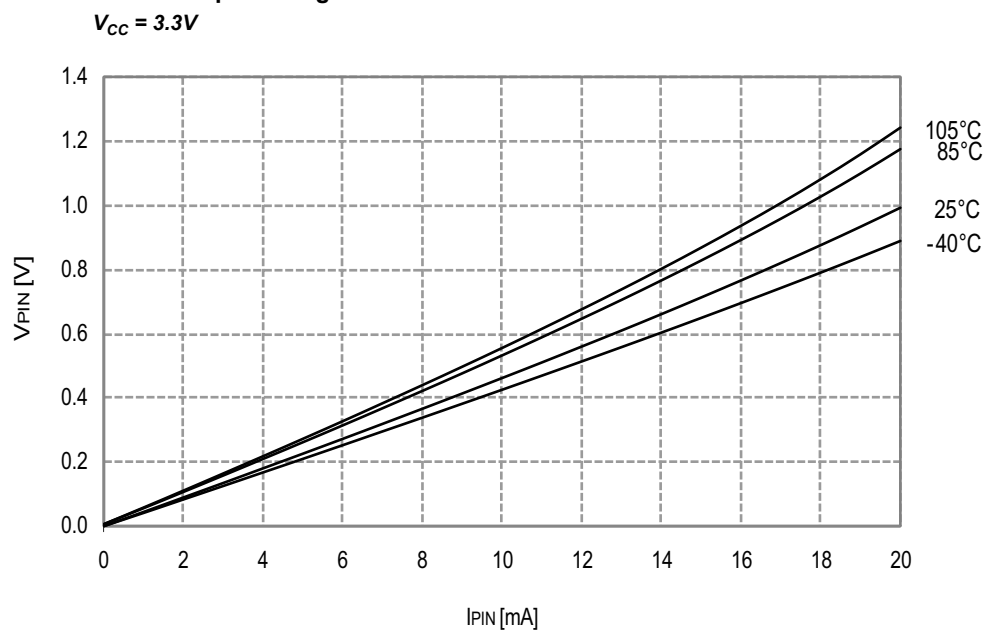


Figure 34-27. I/O Pin Output Voltage vs. Sink Current



34.1.2.3 Thresholds and Hysteresis

Figure 34-28. I/O Pin Input Threshold Voltage vs. V_{CC}

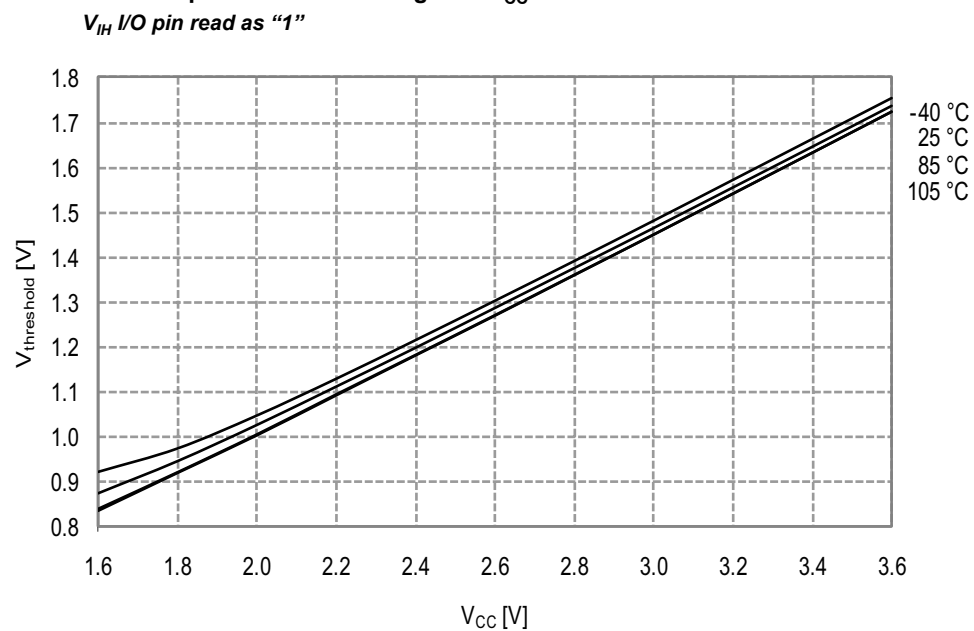


Figure 34-61. 32MHz Internal Oscillator Frequency vs. Temperature
DPLL enabled, from the 32.768kHz internal oscillator

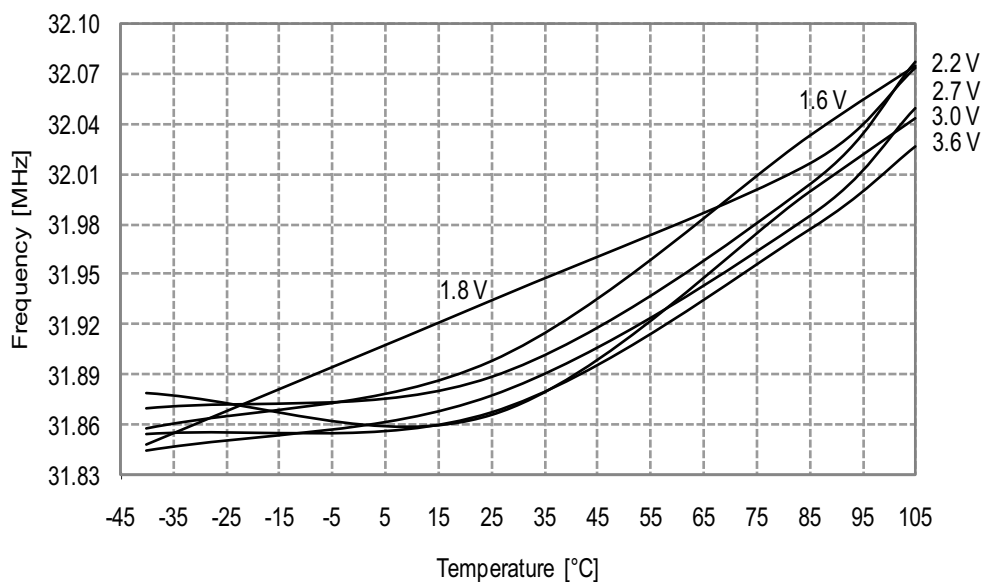
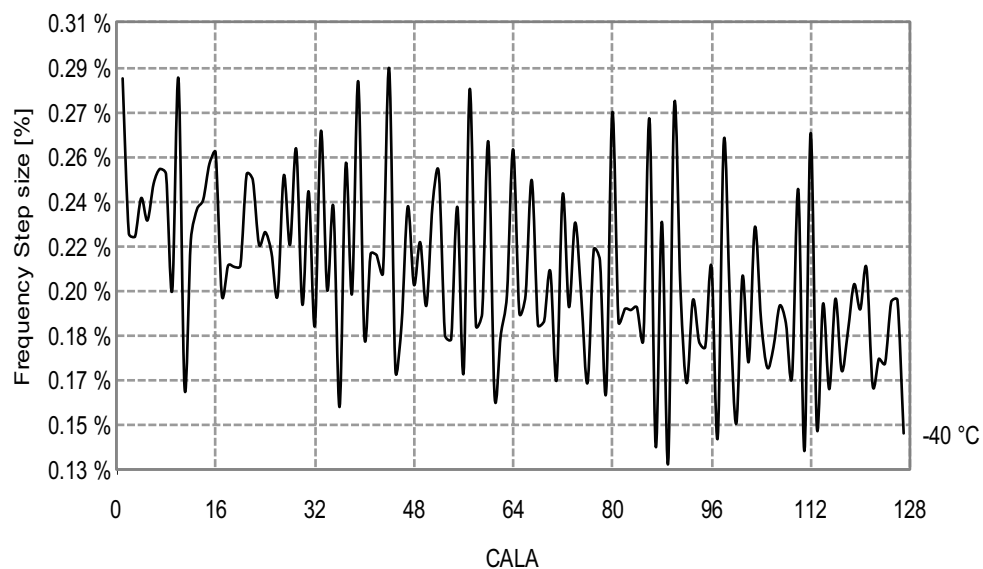


Figure 34-62. 32MHz Internal Oscillator CALA Calibration Step Size
T = -40°C, V_{CC} = 3.0V



34.1.8.5 32MHz Internal Oscillator Calibrated to 48MHz

Figure 34-67. 48MHz Internal Oscillator Frequency vs. Temperature
DPLL disabled

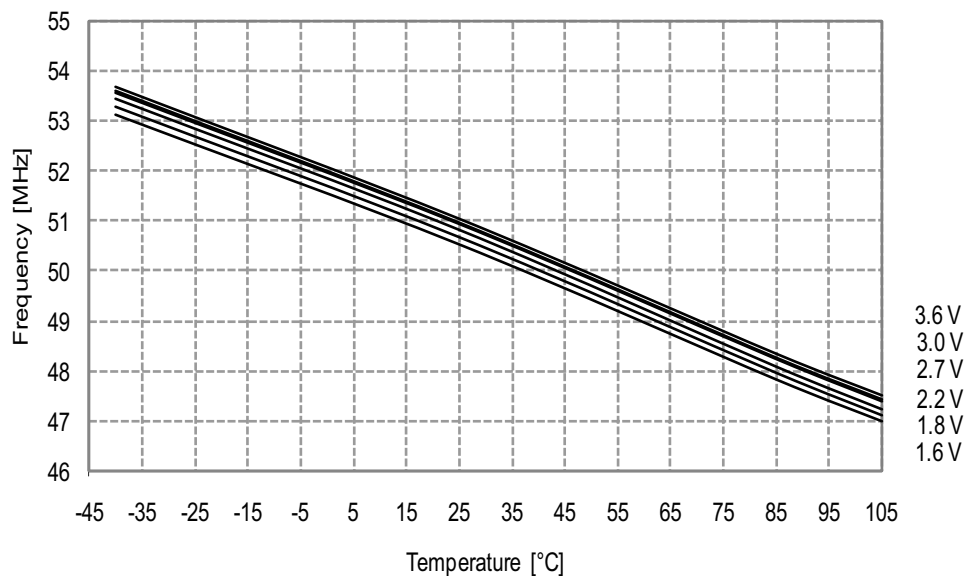
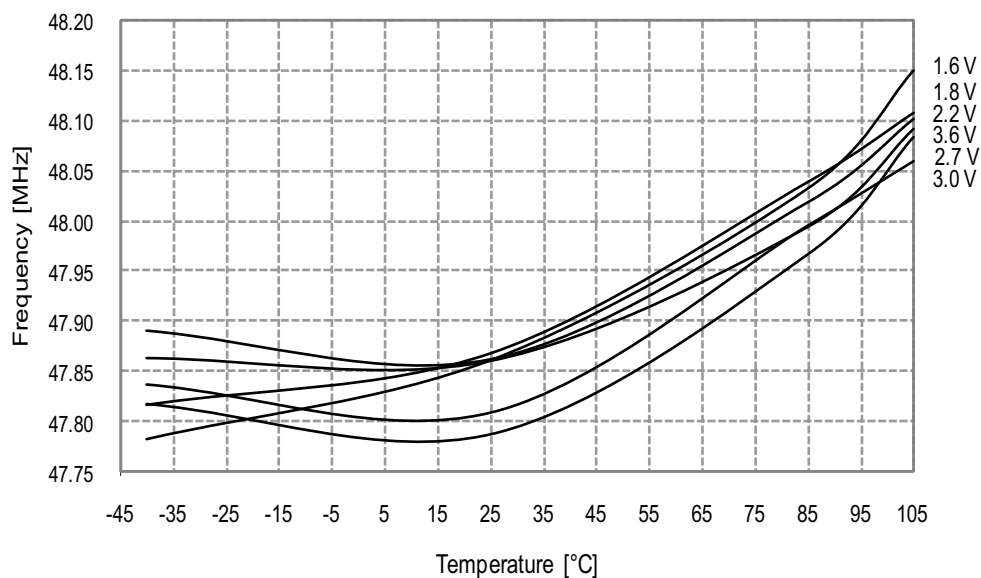


Figure 34-68. 48MHz Internal Oscillator Frequency vs. Temperature
DPLL enabled, from the 32.768kHz internal oscillator



34.2.7 External Reset Characteristics

Figure 34-120. Minimum Reset Pin Pulse Width vs. V_{CC}

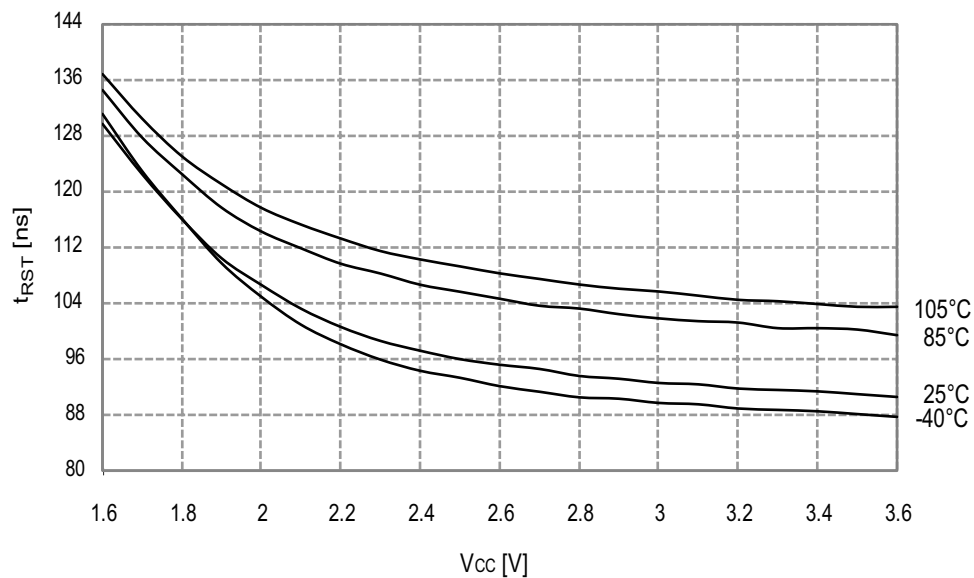


Figure 34-121. Reset Pin Pull-up Resistor Current vs. Reset Pin Voltage
 $V_{CC} = 1.8V$

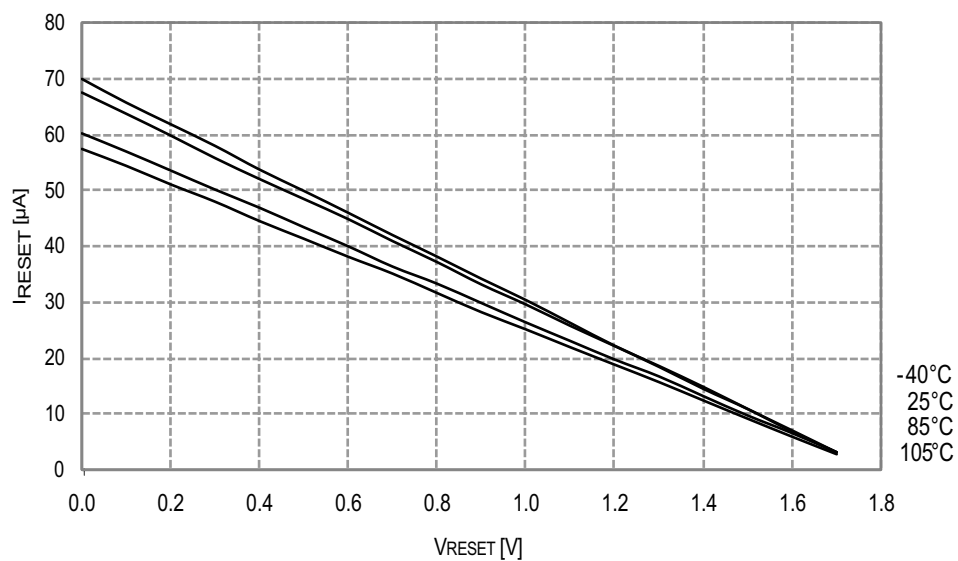


Figure 34-181. Gain Error vs. Temperature

$V_{CC} = 3.0V$, $V_{REF} = \text{external } 2.0V$

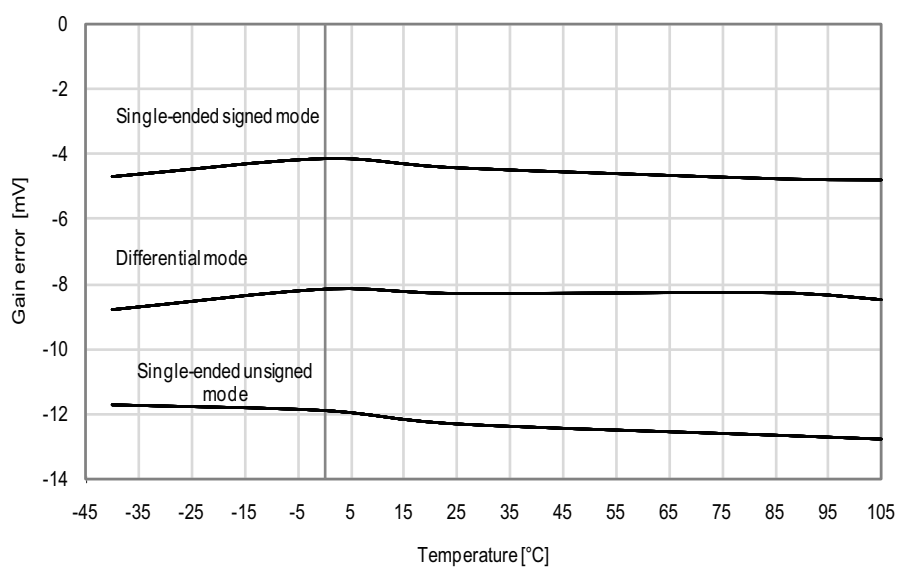
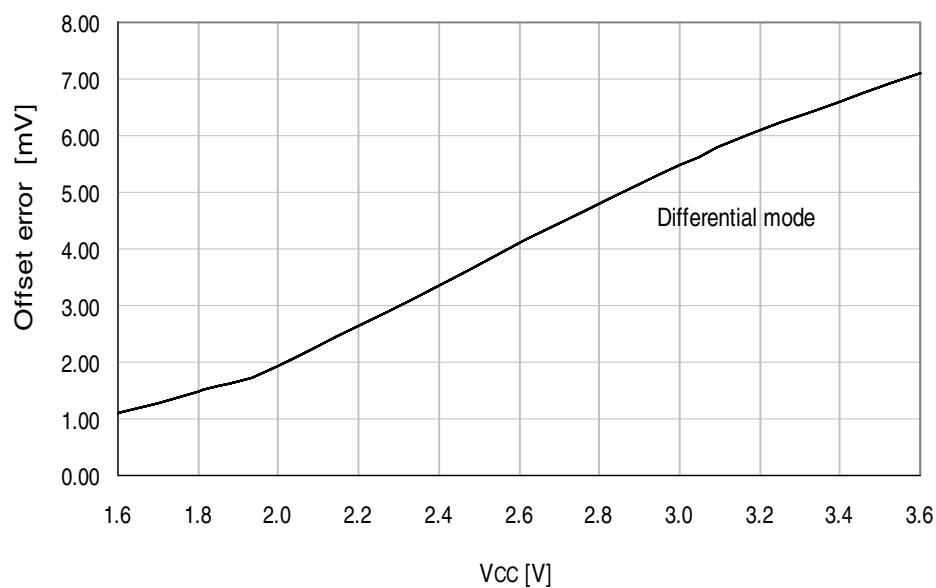


Figure 34-182. Offset Error vs. V_{CC}

$T = 25^{\circ}C$, $V_{REF} = \text{external } 1.0V$, ADC sample rate = 300ksps



34.3.4 Analog Comparator Characteristics

Figure 34-183. Analog Comparator Hysteresis vs. V_{CC}
Small hysteresis

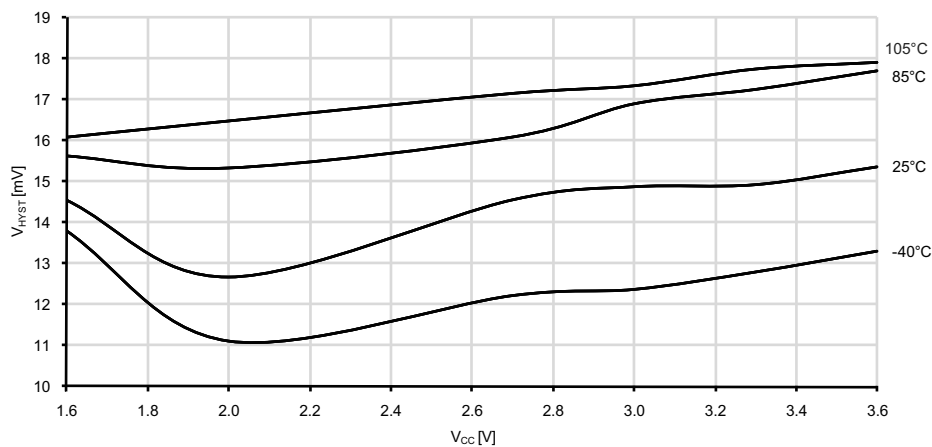


Figure 34-184. Analog Comparator Hysteresis vs. V_{CC}
Large hysteresis

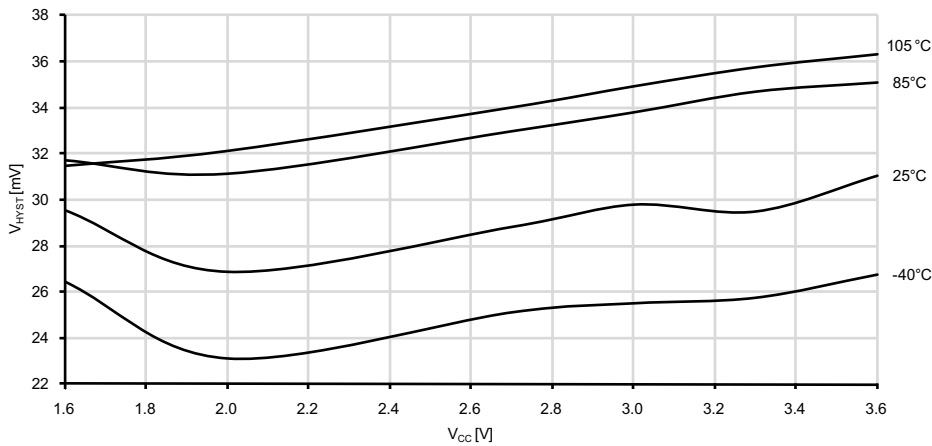


Figure 34-231. I/O Pin Pull-up Resistor Current vs. Input Voltage

$V_{CC} = 3.0V$

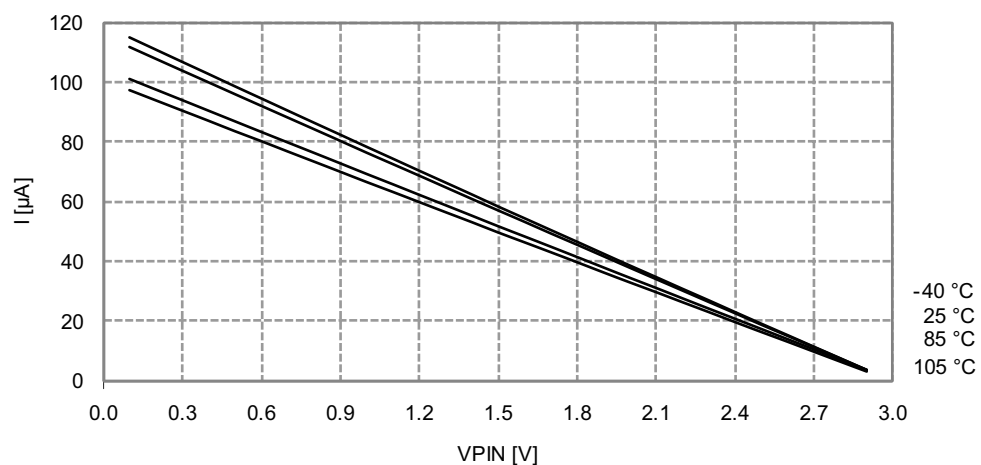
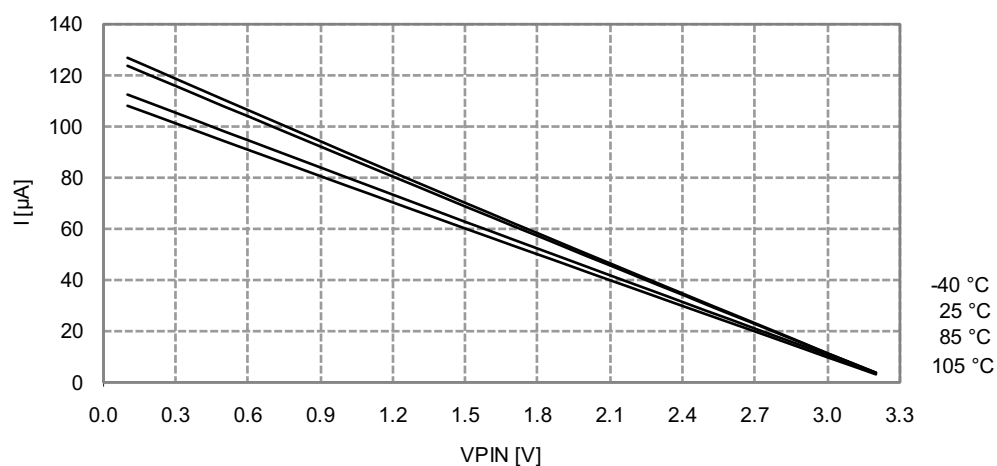


Figure 34-232. I/O Pin Pull-up Resistor Current vs. Input Voltage

$V_{CC} = 3.3V$



34.4.4 Analog Comparator Characteristics

Figure 34-253. Analog Comparator Hysteresis vs. V_{CC}
Small hysteresis

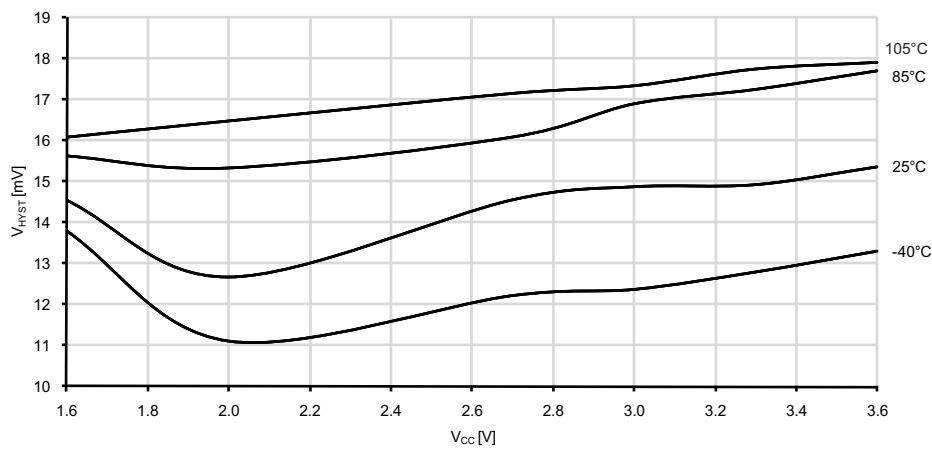


Figure 34-254. Analog Comparator Hysteresis vs. V_{CC}
Large hysteresis

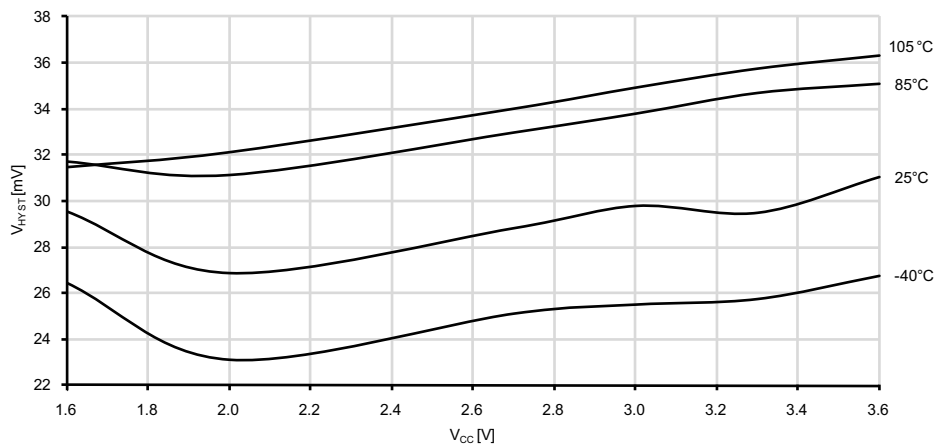


Figure 34-269. 2MHz Internal Oscillator Frequency vs. Temperature
DFLL enabled, from the 32.768kHz internal oscillator

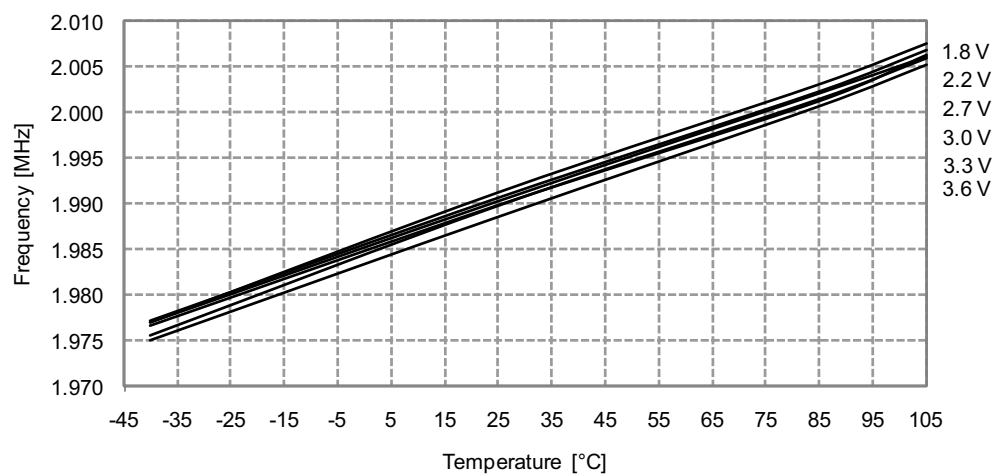


Figure 34-270. 2MHz Internal Oscillator Frequency vs. CALA Calibration Value
 $V_{CC} = 3V$

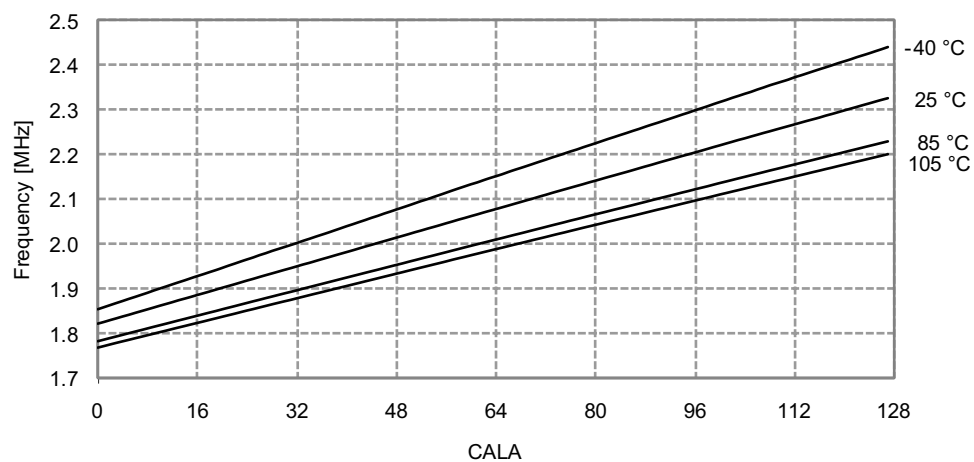
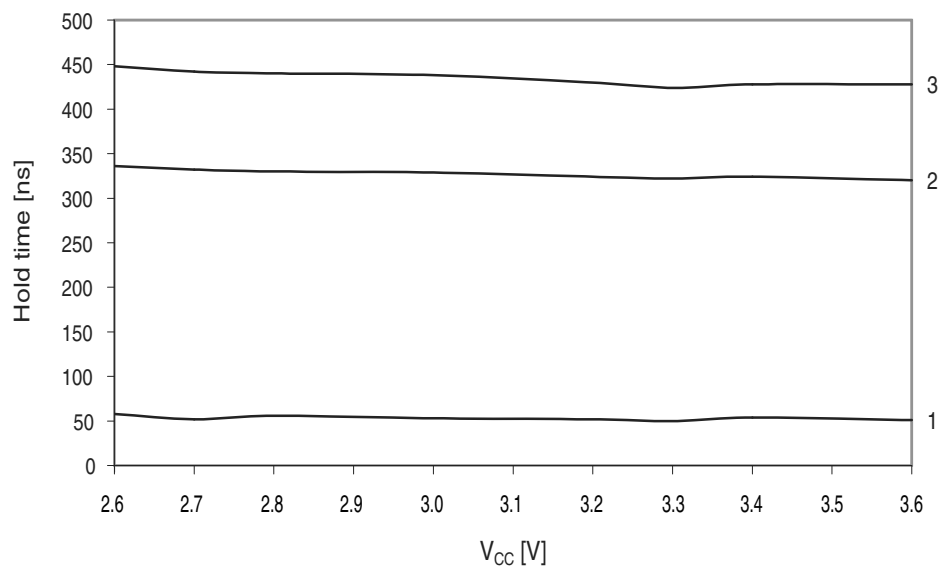


Figure 34-281. SDA Hold Time vs. Supply Voltage



34.4.10 PDI Characteristics

Figure 34-282. Maximum PDI Frequency vs. V_{CC}

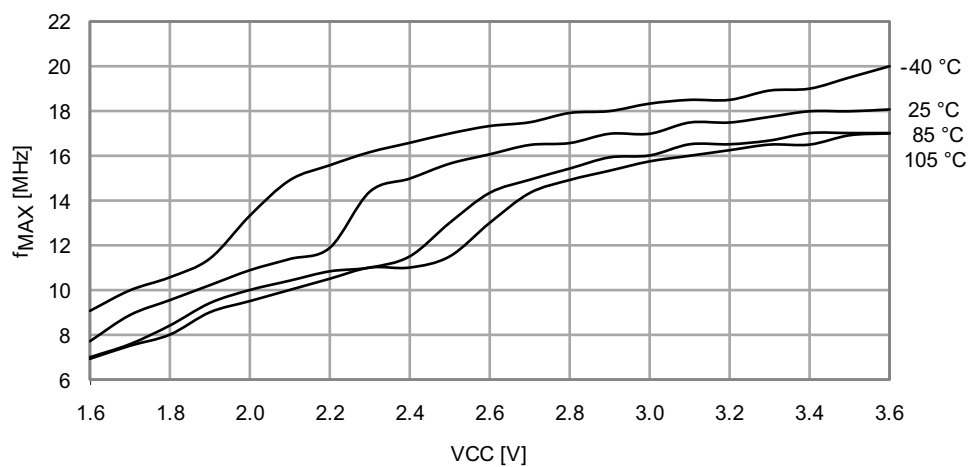


Figure 34-313. INL Error vs. Sample Rate

$T = 25^{\circ}\text{C}$, $V_{CC} = 3.6\text{V}$, $V_{REF} = 3.0\text{V external}$

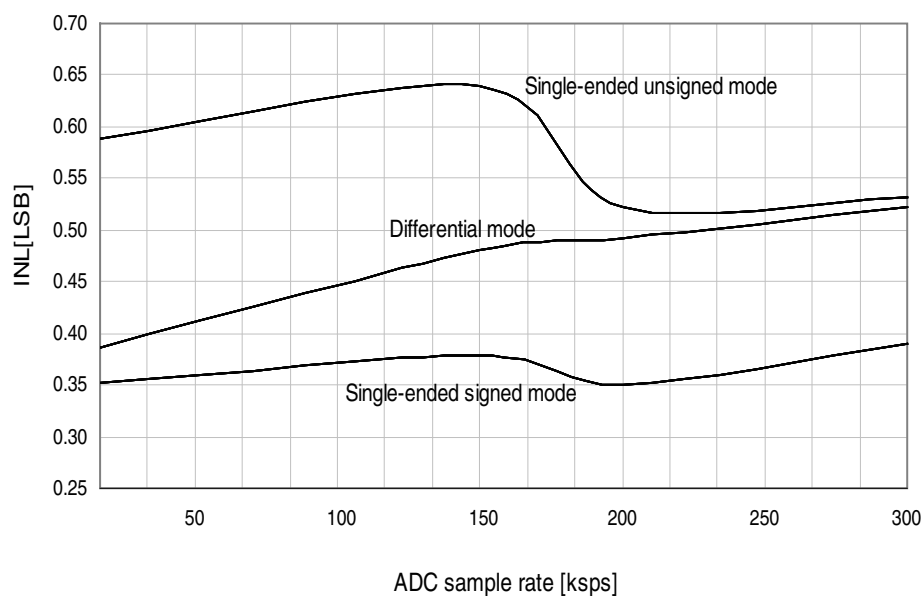


Figure 34-314. INL Error vs. Input Code

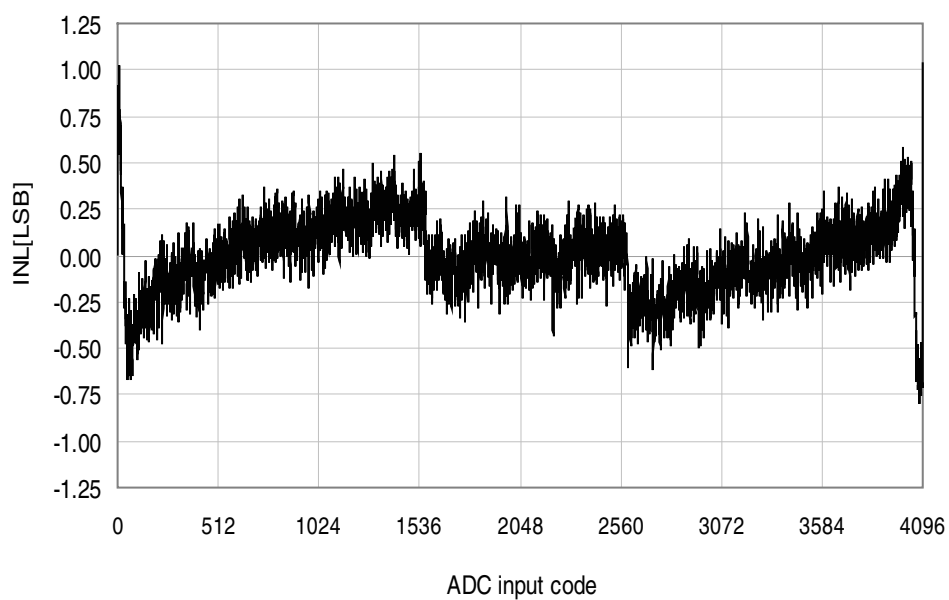
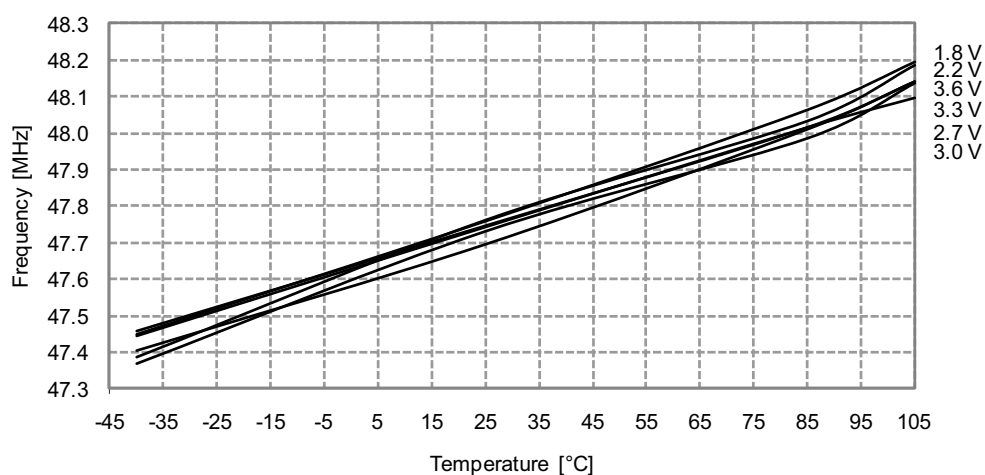
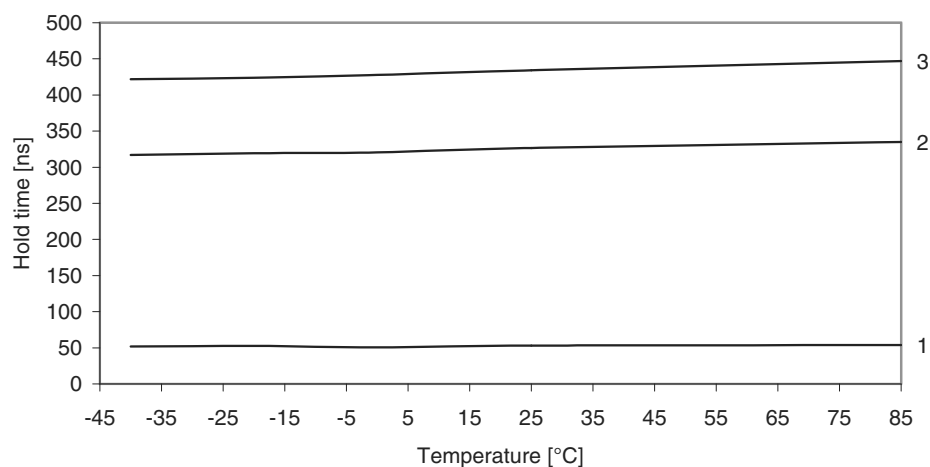


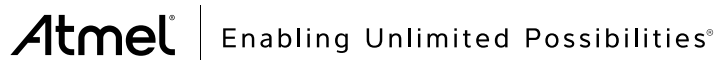
Figure 34-349. 48MHz Internal Oscillator Frequency vs. Temperature
DFLL enabled, from the 32.768kHz internal oscillator



34.5.9 Two-Wire Interface Characteristics

Figure 34-350. SDA Hold Time vs. Temperature





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